

## N-Channel Enhancement Mode MOSFET

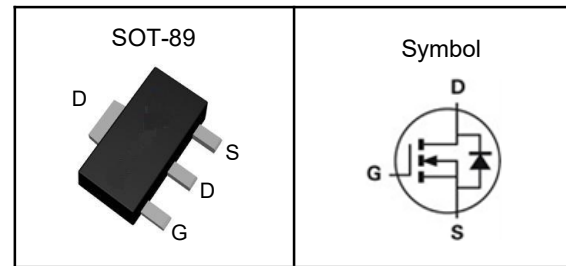
### Features

- Low  $R_{dson}$  for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

### Applications

- Power Management in Desktop Computer
- DC/DC Converters

### Pin Description



$V_{DSS}$	200	V
$R_{DS(ON)-Typ}$	550	m $\Omega$
$I_D$	2	A

### Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	200	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	8	A
$I_D$	Continuous Drain Current	2	A
$P_D$	Maximum Power Dissipation	1.5	W

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	83.3	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

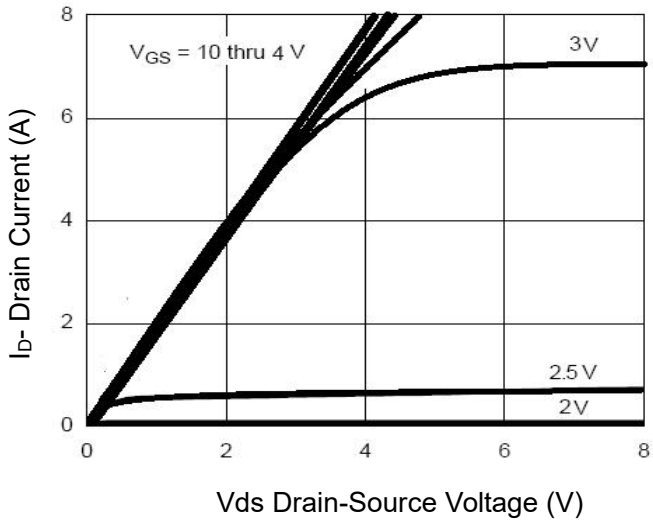
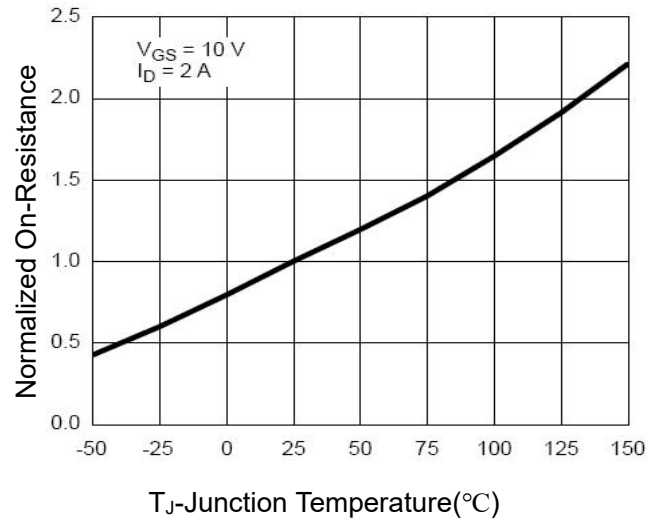
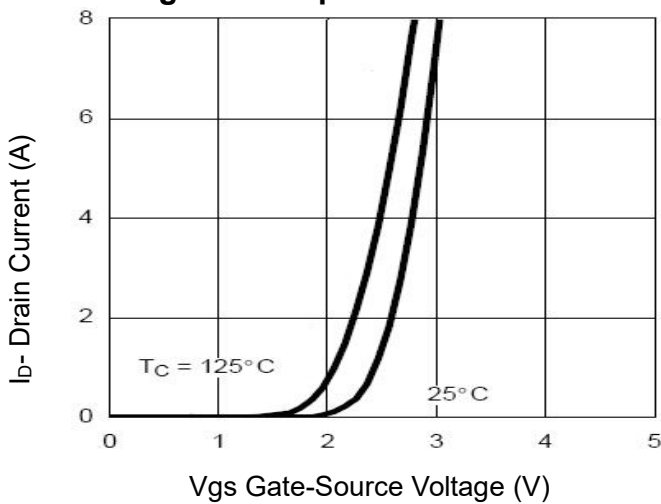
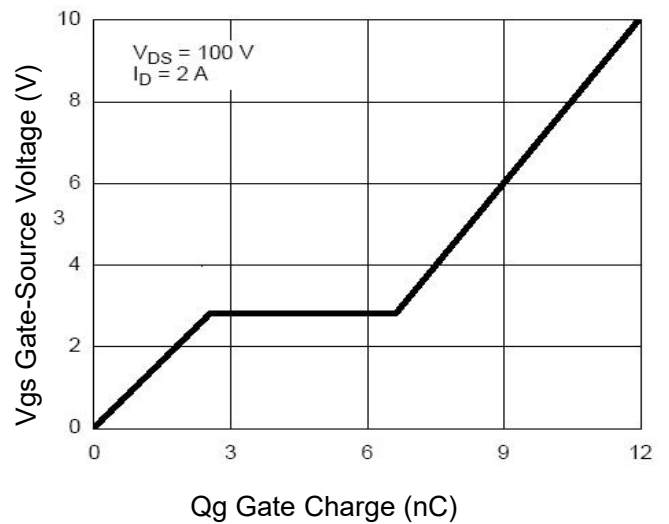
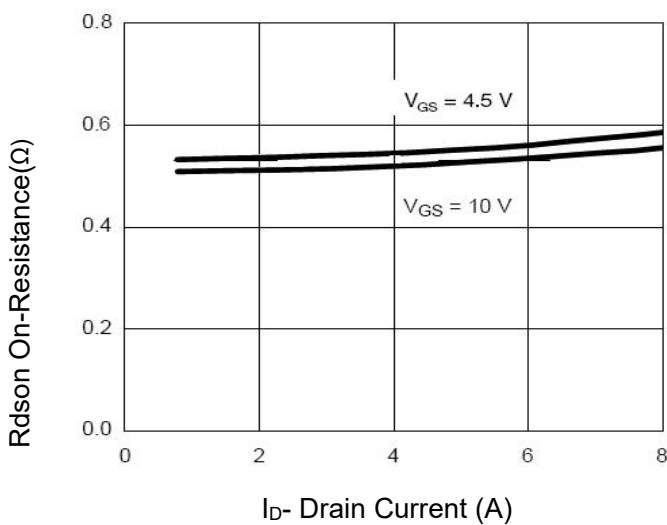
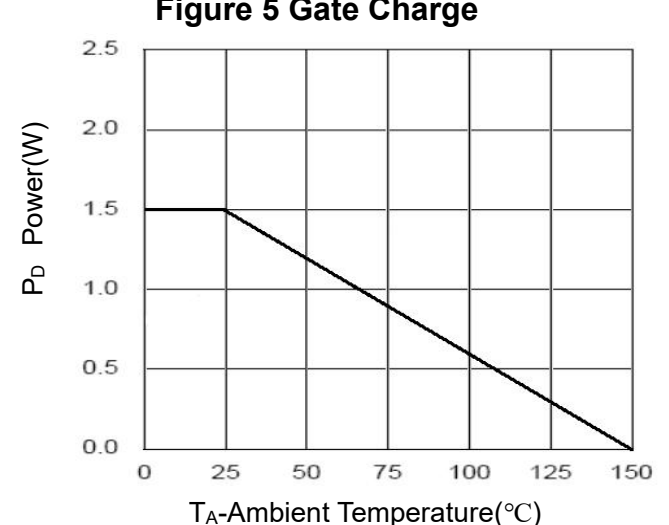
Note ③ : Surface Mounted on  $1\text{in}^2$  FR-4 board with 1oz.

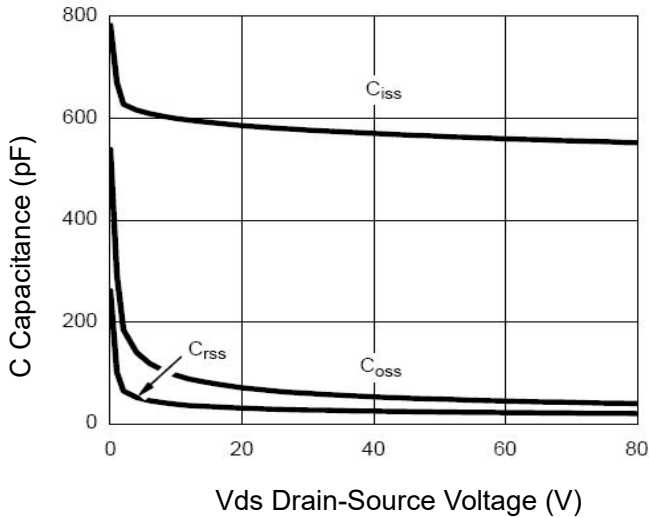
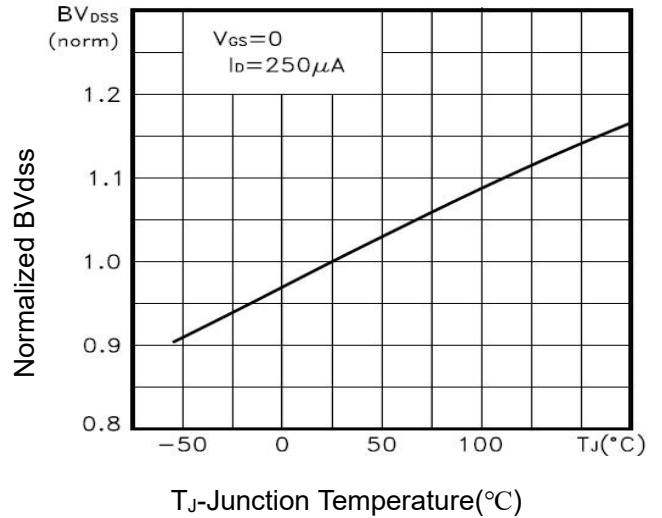
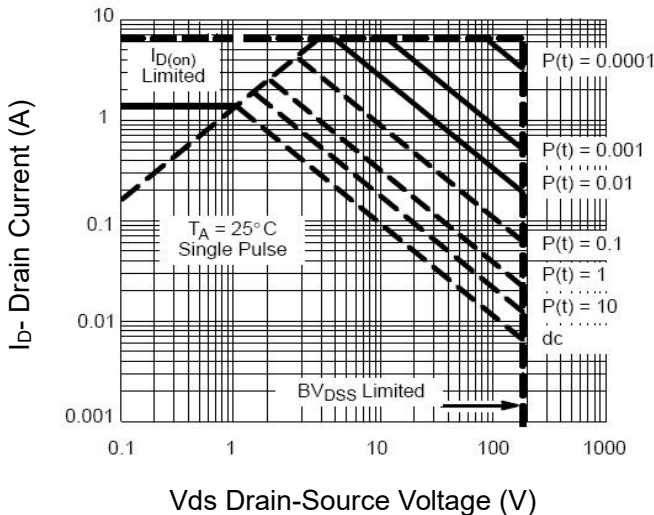
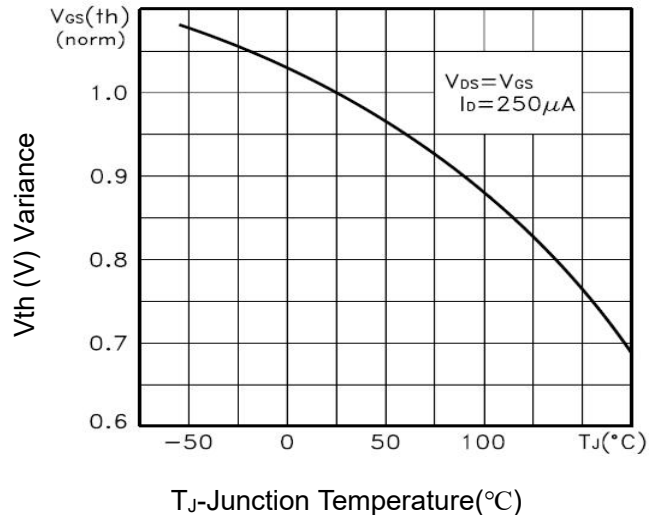
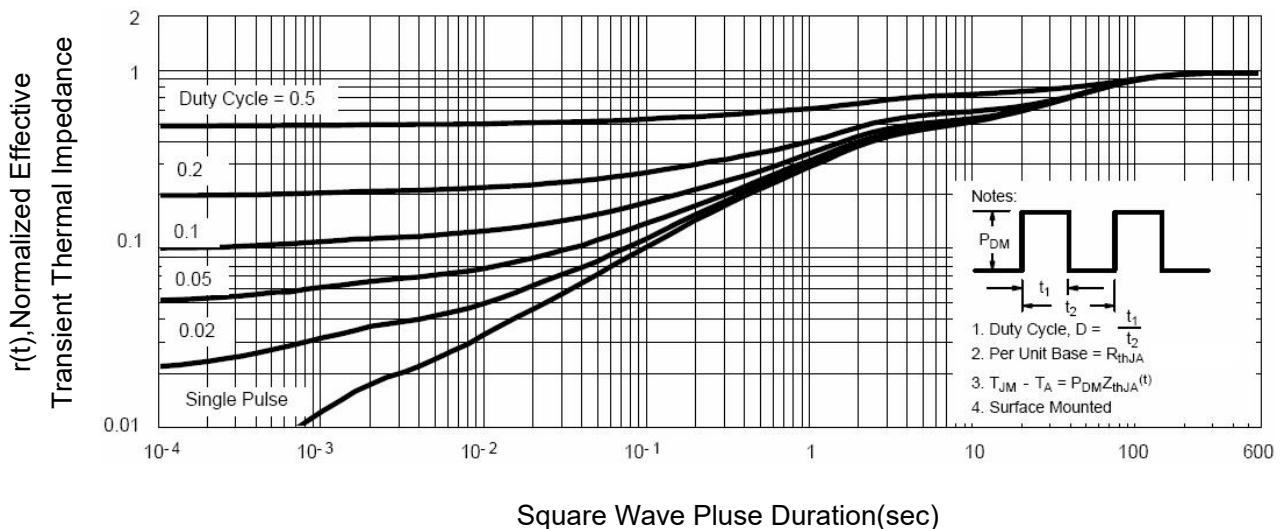
**N-Channel Enhancement Mode MOSFET****Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

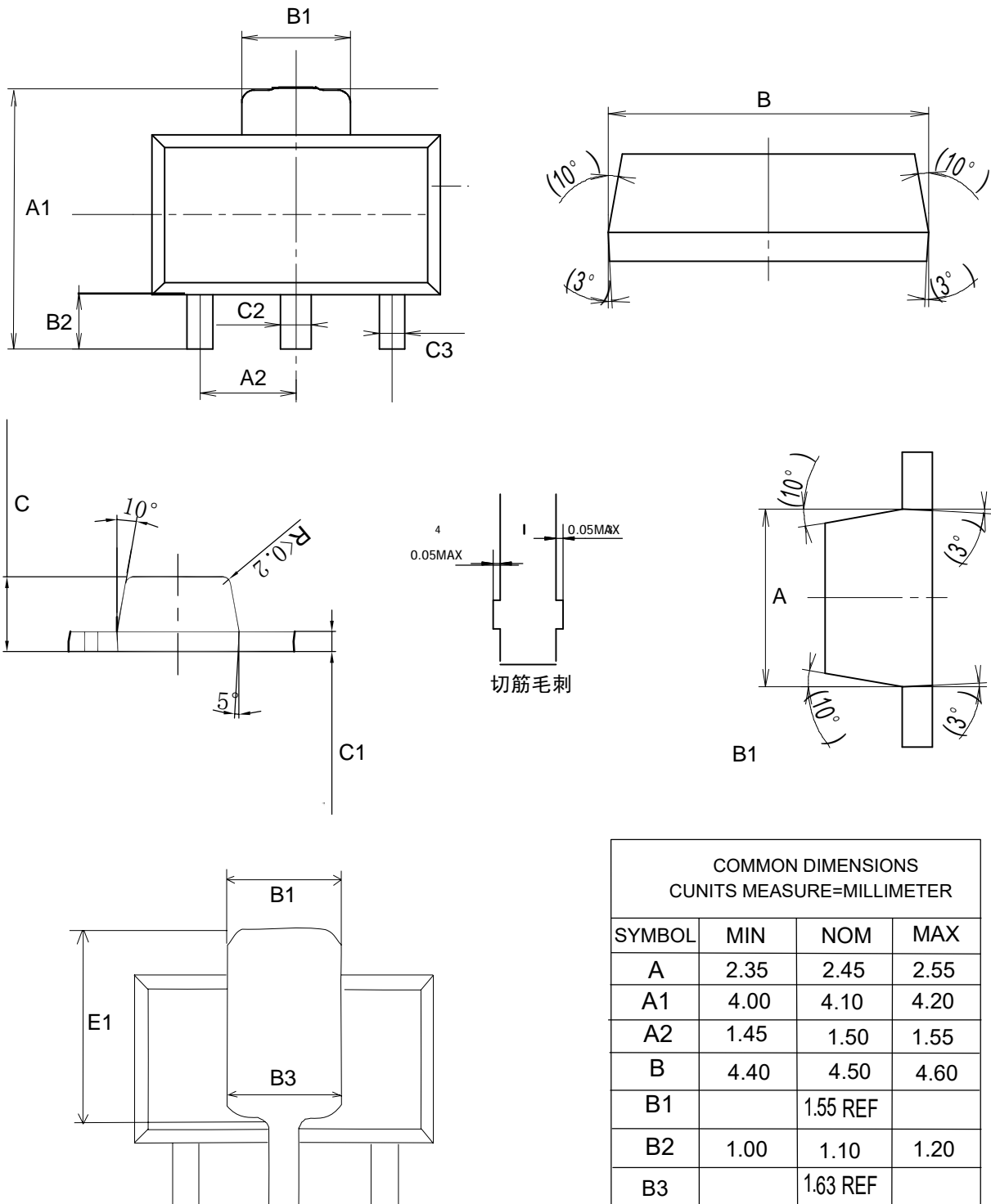
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	200	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=200V, V_{GS}=0V$	---	---	1	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1	---	2	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=2A$	---	550	600	m $\Omega$
		$V_{GS}=4.5V, I_D=2A$	---	570	620	m $\Omega$
<b>Dynamic Characteristics</b> <sup>⑤</sup>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, \text{Freq.}=1\text{MHz}$	---	585	---	pF
$C_{oss}$	Output Capacitance		---	90	---	
$C_{rss}$	Reverse Transfer Capacitance		---	3	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=100V, V_{GS}=10V, R_G=2.5\Omega$	---	10	---	nS
$T_r$	Turn-on Rise Time		---	12	---	
$T_{d(off)}$	Turn-off Delay Time		---	15	---	
$T_f$	Turn-off Fall Time		---	15	---	
$Q_g$	Total Gate Charge	$V_{DS}=100V, V_{GS}=10V, I_D=2A$	---	12	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.5	---	
$Q_{gd}$	Gate-Drain Charge		---	3.8	---	
<b>Source-Drain Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_S=2A, V_{GS}=0V$	---	---	1.2	V

Note ④: Pulse test (pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ ).

Note ⑤: Guaranteed by design, not subject to production testing.

**N-Channel Enhancement Mode MOSFET**
**Typical Characteristics**

**Figure 1 Output Characteristics**

**Figure 4  $R_{dson}$ -Junction Temperature**

**Figure 2 Transfer Characteristics**

**Figure 5 Gate Charge**

**Figure 3  $R_{dson}$ - Drain Current**

**Figure 6 Power Dissipation**

**N-Channel Enhancement Mode MOSFET**

**Figure 7 Capacitance vs Vds**

**Figure 9 BV<sub>DSS</sub> vs Junction Temperature**

**Figure 8 Safe Operation Area**

**Figure 10 V<sub>GS(th)</sub> vs Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

**N-Channel Enhancement Mode MOSFET**
**SOT-89 Package Outline Data**


COMMON DIMENSIONS CUNITS MEASURE=MILLIMETER			
SYMBOL	MIN	NOM	MAX
A	2.35	2.45	2.55
A1	4.00	4.10	4.20
A2	1.45	1.50	1.55
B	4.40	4.50	4.60
B1		1.55 REF	
B2	1.00	1.10	1.20
B3		1.63 REF	
C	1.45	1.50	1.55
C1	0.39	0.40	0.41
C2	0.4	0.48	0.55
C3	0.35	0.4	0.45
E1	2.65	2.75	2.85